ABSTRACT OF THE DISCLOSURE

A thermal interface wafer for facilitating heat transfer from an electronic component to a heat sink. The wafer is formed from at least one elongate, vertically-oriented strip of thermally conductive material having a layer of conformable, heat-conducting material formed thereon. Preferably, the substrate comprises a metal foil, such as aluminum or some other thermally-conductive metal, that is formed as a flat, spiral-like coil. Such strip may further be configured to have a serpentine configuration, or may alternatively be formed from a multiplicity of strips. The present invention further provides for methods of transferring heat from an electronic component to a heat sink, as well as methods for fabricating the thermal interface wafers of the present invention.

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